Patent claims

1. A polymer mixture containing
   - one or more semiconductive polymers,
   - one or more non-semiconductive polymers.

2. The polymer mixture as claimed in claim 1, characterized in that the semiconductive polymer/the semiconductive polymers is/are polythiophene, polyfluorene and/or polythienylenevinylene.

3. The polymer mixture as claimed in either of the preceding claims, characterized in that the non-semiconductive polymer/the non-semiconductive polymers is/are polystyrene, polymethyl methacrylate, cymel and/or polyisobutyl.

4. The polymer mixture as claimed in any of the preceding claims, characterized in that it contains solvents, in particular chloroform, toluene, ketones, dioxane and/or heptane.

5. The polymer mixture as claimed in any of the preceding claims, characterized in that it contains molecules smaller than polymers, in particular oligomers, conductive molecules and/or semiconductive molecules.

6. The polymer mixture as claimed in any of the preceding claims, characterized in that it consists of said substances and customary additives.

7. The polymer mixture as claimed in any of the preceding claims, characterized in that it has a viscosity of more than 8 mPa.s, in particular more than 80 mPa.s.

8. A printing process, in particular screen printing, flexographic printing, offset printing, gravure printing and/or pad printing process, in which a polymer mixture as claimed in any of the preceding claims is used.

9. A double layer containing
   - one or more semiconductive polymers in one of its layers,
   - one or more non-semiconductive polymers in its other layer.

10. A process for the production of a double layer as claimed in claim 9, in which a polymer mixture as claimed in any of claims 1 to 7 is used.

11. An electronic component, in particular circuit, which is produced using a polymer mixture as claimed in any of claims 1 to 7 and/or has a double layer as claimed in claim 9.